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ABSTRACT

A silver alloy sputtering target is provided which is useful in forming a thin silver-alloy film of a uniform thickness by the sputtering method. When crystal orientation strengths are determined at four arbitrary positions by the X-ray diffraction method, the orientation which exhibits the highest crystal orientation strength (X_h) is the same at the four measurement positions, and variations in strength ratio (X_b/X_h) between the highest crystal orientation strength (X_h) and the second highest crystal orientation strength (X_b) is 20% or less.